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I hereby certify that the attached Transmittal (2 pages) and Response to the Final Office Action dated November 23, 2005 (7 pages), are submitted to the U.S. Patent and Trademark Office via facsimile number (571) 273-8300 on the date shown below. (Total 9 pages).



Li Mei Vermilya

Date: February 22, 2006,

RESPONSE UNDER 37 CFR 1.116
EXPEDITED PROCEDURE
EXAMINING GROUP 2822

PATENT APPLICATION
Docket No.: 9903-071
Client Ref. No.: S02US035

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Jin-Hyuk LEE, et al.

Serial No.: 10/690,782 Examiner: Graybill, David E.

Filed: October 21, 2003 Group Art Unit: 2822

Confirmation No.: 5611

For: METHOD FOR MANUFACTURING A WAFER LEVEL CHIP
SCALE PACKAGE

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Responsive to the Final Office Action November 23, 2005, enclosed is an amendment in the above-identified application.

The fee has been calculated as shown below.

CLAIMS AS AMENDED					
For:	Number After Amendment	Previous Number	Extra	Rate	Additional Fee
Total Claims	17	19	0	x \$50 =	\$0
Independent Claims	4	4	0	x \$200 =	\$0
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0

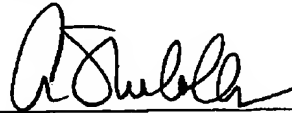
*greater of twenty (20) or number for which fee has been paid
**greater of three (3) or number for which fee has been paid

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Customer No. 20575

Respectfully submitted,

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SCALE PACKAGEMail Stop AF
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P.O. Box 1450
Alexandria, VA 22313-1450**AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR 1.116**

Responsive to the Final Office Action, Paper No. 20051119, dated November 23, 2005, please amend the application as follows.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.